

Serial No. 10/814,180

LISTING OF CLAIMS:

The following listing of claims replaces all previous versions and listings of claims in the present application.

Please cancel claims 1-5, and 8.

1. – 5. (Canceled)

6. (Currently Amended) A resin-sealed semiconductor device in which a semiconductor device formed by disposing an undersurface of a semiconductor chip on one side of an island portion of a lead frame and connecting the surface of the semiconductor chip to lead portions of the lead frame disposed around the semiconductor chip with plural bonding wires, is sealed with resin in a state where portions of the lead portions are exposed, the resin-sealed semiconductor device comprising:

an injection mark of the resin disposed directly above the surface of the semiconductor chip; and

a recessed portion disposed in an end surface of the resin, wherein the top of the injection mark is made lower than the end surface.

7. (Original) The resin-sealed semiconductor device of claim 6, further comprising a support board for supporting the island portion disposed at the other side of the island portion.

8. (Canceled).